

chamber **512**, a passivation film (such as SiN and SiOx films) for protecting the surface is deposited by sputtering or CVD in general.

[0102] The substrate after the deposition is carried to a transport chamber **514** through a delivery chamber **513**. The transport chamber **514** is connected to a plurality of chambers necessary for encapsulation. The transport chamber **514** is also installed with a transfer robot for serving to transport substrates or encapsulation substrates to each chamber connected to the transport chamber **514**.

[0103] First, substrates for encapsulation need to be prepared. The chambers for the purpose are an encapsulation glass substrate preparation chamber **515a** and an encapsulation plastic substrate preparation chamber **515b**.

[0104] To the encapsulation glass substrate preparation chamber **515a**, an opposite glass for encapsulating the fabricated organic light emitting diode with glass is introduced from outside. A desiccant for protecting the organic light emitting diode against water can be introduced into the opposite glass as necessary. For example, it is fine to bond a sheet-shaped desiccant to the spot-faced recess of the opposite glass where spot facing has been applied beforehand with a double-face tape.

[0105] In the meantime, in the encapsulation plastic substrate preparation chamber **515b**, encapsulation is prepared for encapsulating the fabricated organic light emitting diode with plastic. It is fine to introduce a plastic (finished product) having a shape matched to the purpose from outside. In the embodiment, however, a support (it is plastic in the embodiment) of the invention is fabricated in the encapsulation plastic substrate preparation chamber **515b**. For example, the support with curvature and elasticity is fabricated according to the materials and methods described by **FIGS. 2A and 2B**. More specifically, the molds **211a** and **211b** and the thermosetting resin **212** are introduced from outside for shaping such as heating, pressing and cooling. When the organic light emitting diode is transferred onto a plastic, it is fine to fabricate the transfer object in the invention as well in the similar manner. The work may be fully automated or may be partially manually operated by disposing gloves.

[0106] The prepared encapsulation glass substrate or encapsulation plastic substrate is carried to a dispenser chamber **516** and an adhesive (not shown) for bonding it to a substrate later is applied. In the embodiment, an adhesive of the UV curable type is used for the adhesive. Furthermore, a desiccant for protecting the organic light emitting diode from water (not shown) may be disposed in the dispenser chamber **516** not in introducing the glass substrate into the encapsulation glass substrate preparation chamber **515a**. For example, a sheet-shaped desiccant can be bonded to the spot-faced recess of the opposite glass where spot facing has been applied with a double-face tape. Accordingly, the desiccant does not need to be handled in the atmosphere. As for the work, it may be fully automated or may be partially manually operated by disposing gloves. Particularly, when the encapsulation plastic substrate has curvature and elasticity, the adhesive may be coated with the substrate curved or may be coated with it stretched straight.

[0107] The substrate after deposition and the encapsulation glass substrate or encapsulation plastic substrate coated with the adhesive are carried to an encapsulation chamber

**517**, and they are bonded to each other. It is necessary to use a proper jig (not shown) to press them in bonding. It is fine to bond the encapsulation plastic substrate with curvature and elasticity with it stretched straight. As for the work, it may be fully automated or may be partially manually operated by disposing gloves.

[0108] Subsequently, the substrate and the encapsulation substrate, which have been bonded to each other in the encapsulation chamber **517**, are carried to a UV irradiation chamber **518** and ultraviolet rays for curing the adhesive are irradiated onto them.

[0109] It is fine to bring the substrate and the encapsulation substrate out of a delivery chamber **519** to outside, which have been bonded in the UV irradiation chamber **518**.

[0110] However, when the device in the invention is fabricated, two steps are further needed, removing the substrate and bonding the transfer object as shown in **FIGS. 1D and 1E**. More specifically, the substrate and the encapsulation substrate (support), which have been bonded in the UV irradiation chamber **518**, are again brought back to the encapsulation plastic substrate preparation chamber **515b**. The substrate is peeled in the encapsulation plastic substrate preparation chamber **515b**. In the embodiment, the method of utilizing the membrane stress between the metal layer or nitride layer and the oxide layer is used for the peeling method. In the meantime, as similar to the support, the transfer object is carried to the dispenser chamber **516** from the encapsulation plastic substrate preparation chamber **515b**, and the adhesive is applied to it. The support peeled off the substrate and the transfer object coated with the adhesive are carried to the encapsulation chamber **517**, and they are bonded to each other. After that, they are carried to the UV irradiation chamber **518** for UV irradiation, whereby the display device is completed. Finally, it is fine to bring the finished product out of the delivery chamber **519** to outside.

[0111] Besides, the embodiment can be combined with the embodiment 1.

[0112] [Embodiment 4]

[0113] The embodiment shows the example of installing the display with curvature obtained by the invention on a vehicle. Here, an automobile was used as a typical example of the vehicles, but the invention is not limited particularly, without saying that it can be adapted to aircrafts, trains and electric railcars.

[0114] **FIG. 6** is a diagram illustrating around the driver seat of an automobile. In a dashboard part, audio systems, specifically a car audio system and a navigation system, are disposed. A main body **2701** of the car audio system includes a display part **2702**, and operating switches **2703** and **2704**. The invention is implemented to the display part **2702**, whereby a low-profile, light-weight car audio system can be completed. In addition, the invention is implemented to a display part **2801** of the car navigation system, whereby a low-profile, light-weight car navigation system can be completed.

[0115] Furthermore, near an operating handle part **2605**, a display part **2603** for digital display of meters such as a speedmeter is formed on the dashboard part **2601**. The invention is implemented to the display part **2702**, whereby a low-profile, light-weight display for meters can be completed.